

A COPPER ALLOY SUITABLE FOR AN IC LEAD PIN FOR A PIN GRID
ARRAY PROVIDED ON A PLASTIC SUBSTRATE

FIELD OF THE INVENTION

5 The present invention relates to a copper alloy
suitable for materials of an IC lead pin for a pin grid
array (hereinafter, simply referred to as an IC lead pin
for PGA) provided on a plastic substrate.

10 BACKGROUND

 An IC lead pin for PGA is provided by blazing, to be
an electric input/output terminal on a back surface of a
substrate having a semiconductor element mounted thereon.
As the substrate, use has been made of a ceramics material.
15 For the IC lead pin for PGA, mainly use has been made of
Kovar (an Fe-Ni-Co alloy) that has a low thermal expansion
coefficient equal to that of the ceramics substrate and
that is excellent in tensile stress and repeated bending
property.

20 In recent years, there has been a tendency to use a
plastic substrate as the above substrate. In the case of
such a plastic substrate, there is no need to employ a
material with a low thermal expansion coefficient for an
IC lead pin for PGA.

25 On the other hand, in order to improve function of

IC, it is desired to ensure speedy transmission in a CPU (central processing unit) and provide a highly dense IC, and a material with high conductivity is required for an IC lead pin for PGA.

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SUMMARY

The present invention is a copper alloy suitable for an IC lead pin for a pin grid array provided on a plastic substrate, which copper alloy is one alloy selected from the group consisting of:

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a copper alloy containing 0.05 to 0.5 wt% of Zn and 0.05 to 0.5 wt% of Mg, with the balance being made of unavoidable impurities and Cu;

a copper alloy containing 0.1 to 1.0 wt% of Sn, with the balance being made of unavoidable impurities and Cu;

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a copper alloy containing 0.1 to 1.0 wt% of Sn and 0.1 to 0.6 wt% of Ag, with the balance being made of unavoidable impurities and Cu;

a copper alloy containing 2.1 to 2.6 wt% of Fe, 0.05 to 0.2 wt% of Zn, and 0.015 to 0.15 wt% of P, with the balance being made of unavoidable impurities and Cu; and

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a copper alloy containing 0.4 to 1.1 wt% of Cr, with the balance being made of unavoidable impurities and Cu,

wherein the copper alloy has conductivity of 50% IACS or more and tensile stress of 400 MPa or more but 650

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MPa or less.

Other and further features and advantages of the invention will appear more fully from the following description.

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DETAILED DESCRIPTION

The inventors conducted research to find an IC lead pin for PGA provided on a plastic substrate, with the lead pin being capable of coping with speedy CPU transmission and providing a highly dense IC. As a result, we found that the characteristics required therefor are conductivity of 50% IACS or more, tensile stress equal to Kovar, and high repeated bending property. We conducted further research to complete the present invention.

15 The copper alloy of the present invention is a copper alloy suitable for an IC lead pin for a grid array provided on a plastic substrate, with the copper alloy being any one of five kinds of copper alloys, i.e., a Cu-Zn-Mg alloy, a Cu-Sn alloy, a Cu-Sn-Ag alloy, a Cu-Fe-Zn-P alloy, and a Cu-Cr alloy, wherein the quantities of each alloy elements are properly defined, thereby the copper alloy being provided conductivity of 50% IACS or more, tensile stress of 400 MPa or more but 650 MPa or less, and practically-allowable level of repeated bending property
20
25 can be given.

FIG. 10

In the present invention, the conductivity is set to 50% IACS or more, because the conductivity of less than 50% IACS cannot cope with speedy CPU transmission or provide a highly dense IC satisfactorily. In addition, 5 the tensile stress is set to 400 MPa or more but 650 MPa or less, because tensile stress of less than 400 MPa may damage a pin during IC assembling and using, and sufficient repeated bending property may not be obtained if the tensile stress exceeds 650 MPa.

10 Alloy elements and compositions of the five kinds of copper alloys for use in the present invention will be described below.

In the above Cu-Zn-Mg alloy, alloy elements Zn and Mg contribute to improve mechanical strength. In this 15 copper alloy, the contents of Zn and Mg are 0.05 to 0.5 wt%, respectively. This is because sufficient tensile stress cannot be obtained if either one of the contents is less than the lower limit, and sufficient conductivity or repeated bending property cannot be obtained if either one 20 of the contents exceeds the upper limit.

In the Cu-Sn alloy, an alloy element, Sn, contributes to improve mechanical strength. In this copper alloy, the content of Sn is defined within the range of 0.1 to 1.0 wt%. This is because sufficient 25 tensile stress cannot be obtained if the content is less

than 0.1 wt%, and sufficient conductivity or repeated bending property cannot be obtained if the content is more than 1.0 wt%.

In the Cu-Sn-Ag alloy, Sn and Ag contribute to improve mechanical strength. In this copper alloy, the Sn content is defined within the range of 0.1 to 1.0 wt%, and the Ag content is defined within the range of 0.1 to 0.6 wt%. This is because sufficient tensile stress cannot be obtained if either one of the contents is less than the lower limit, and sufficient conductivity or repeated bending property cannot be obtained if either one of the contents exceeds the upper limit. Further, Ag in a too high content is disadvantageous to cost efficiency because Ag is expensive.

In the Cu-Fe-Zn-P alloy, Fe, Zn and P contribute to improve mechanical strength. In this copper alloy, the Fe content is defined within the range of 2.1 to 2.6 wt%, the Zn content is defined within the range of 0.05 to 0.2 wt%, and the P content is defined within the range of 0.015 to 0.15 wt%, respectively. This is because sufficient tensile stress cannot be obtained if any one of these contents is less than the lower limit, and sufficient conductivity or repeated bending property cannot be obtained if any one of the contents exceeds the upper limit.

In the Cu-Cr alloy, Cr contributes to improve mechanical strength. In this copper alloy, the Cr content is defined within the range of 0.4 to 1.1 wt%. This is because sufficient tensile stress cannot be obtained if the content is less than 0.4 wt%, and sufficient conductivity or repeated bending property cannot be obtained if the content exceeds 1.1 wt%.

The copper alloy of the present invention can be manufactured in a usual manner, for example, by applying melt-casting, hot-working (such as extrusion or rolling), and drawing (including wire-drawing) all of the preceding, one after another, in this order. Although the characteristics such as conductivity or tensile stress, are mainly determined depending on alloy composition, they can be adjusted by selecting heat treatment conditions, such as intermediate annealing applied in mid course of drawing.

Preferable conditions in each of the above steps are as follows. The melt-casting is preferably carried out at a temperature of 1,100 to 1,300 °C. The hot-working, such as extrusion, is preferably carried out at a temperature of 700 to 900 °C for 2 to 4 hours. The intermediate annealing is preferably carried out at a temperature of 400 to 600 °C for 2 to 4 hours.

The copper alloy of the present invention has

conductivity that can adequately cope with speedy CPU transmission or provide a highly dense IC, it has tensile stress equal to conventional Kovar, and it has practically-sufficient level of high repeated bending property. Accordingly, the copper alloy of the present invention is preferable for an IC lead pin for PGA provided on a plastic substrate. Therefore, the present invention exhibits a significant advantageous effect from the industrial viewpoint.

10 The present invention will be described in more detail by way of the following examples, but the invention is not limited to these.

EXAMPLES

15 (Example 1)

A Cu-Zn-Mg alloy, a Cu-Sn alloy, a Cu-Sn-Ag alloy, a Cu-Fe-Zn-P alloy, and a Cu-Cr alloy, with their compositions defined in the present invention, were melt-casted in a usual manner, to make a cast ingot, respectively. Each cast ingot was subjected to hot extrusion and then drawing, in this order. Then, wire drawing was carried out, and in mid course thereof an intermediate annealing was carried out, to produce a rod of 0.4 mm in diameter, respectively. The conditions in the above steps were as follows. The melt-casting was

carried out at a temperature of 1,100 to 1,300 °C. The
extrusion was carried out at a temperature of 700 to 900
°C for 2 to 4 hours. The intermediate annealing was
carried out at a temperature of 400 to 600 °C for 2 to 4
5 hours.

(Comparative Example 1)

A rod of 0.4 mm in diameter was produced in the same
manner as in Example 1 except that the composition of each
copper alloy was set to be outside the definition in the
10 present invention.

The tensile stress, conductivity, and repeated
bending property were examined with respect to each of the
rods manufactured in Example 1 and Comparative Example 1.
Further, the adhesion of Au plating applied to an IC lead
15 pin for PGA was also examined.

The tensile stress was measured by carrying out a
test according to JIS Z 2241, using a test piece produced
from each rod according to JIS Z 2201.

The conductivity was measured by carrying out a test
20 according to JIS H 0505, using a test piece produced from
each rod according to JIS H 0505.

The repeated bending property was evaluated by
counting the number of bending operations, in which a
weight of 230 g was suspended at one end of the rod, and
25 90-degree bending operation was carried out in the right

and left (horizontal) direction until breakage occurred. The number of bending operations was counted, with one reciprocation defined as one count. If the number of bending operations is 6 or more, there is no practical
5 problem. Thus, a number of 6 or more bending operations was judged to be good (allowable).

The adhesion of Au plating was examined by applying plating of Au to each rod in a usual manner, and twist-testing each rod with Au plating. The twisting test was
10 carried out under conditions in which after 50 rotations in one rotation direction, were done 40 rotations in the inverse direction, with a distance of 50 mm between chucks. The presence or absence of peeling of Au plating was judged by observation with the naked eye.

15 The results are shown in Table 1.

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Table 1

Classification	No.	Alloy	Alloy composition wt%							Tensile stress (Mpa)	Conductivity (%IACS)	Repeated bending property (Number)	Adhesion of Au plating
			Zn	Mg	Sn	Ag	Fe	P	Cr				
Examples according of this invention	1	Cu-Zn	0.1	0.2	-	-	-	-	-	540	75	8	Good
	2	-Mg	0.3	0.5	-	-	-	-	-	570	66	7	Good
	3	Cu-Sn	-	-	0.7	-	-	-	-	580	62	7	Good
	4	-	-	-	1.0	-	-	-	-	620	52	6	Good
	5	Cu-Sn	-	-	0.6	0.3	-	-	-	560	59	7	Good
	6	-Ag	-	-	1.0	0.3	-	-	-	640	50	6	Good
	7	Cu-Zn	0.1	-	-	-	2.1	0.1	-	440	68	13	Good
	8	-Fe-P	0.1	-	-	-	2.5	0.1	-	480	64	10	Good
	9	-	0.2	-	-	-	2.1	0.1	-	460	66	12	Good
	10	-	0.2	-	-	-	2.5	0.1	-	500	62	9	Good
Comparative examples	11	Cu-Cr	-	-	-	-	-	-	0.5	500	91	8	Good
	12	-	-	-	-	-	-	-	0.1	550	85	7	Good
	13	Cu-Zn	0.02	0.04	-	-	-	-	-	370	88	9	Good
	14	-Mg	0.8	0.6	-	-	-	-	-	650	28	3	Good
	15	Cu-Sn	-	-	0.05	-	-	-	-	340	95	14	Good
	16	-	-	-	2.0	-	-	-	-	670	28	3	Good
	17	Cu-Sn	-	-	0.05	0.05	-	-	-	360	75	9	Good
	18	-Ag	-	-	2.0	1.0	-	-	-	680	30	3	Good
	19	Cu-Zn	0.03	-	-	-	1.8	0.1	-	360	70	13	Good
	20	-Fe-P	0.3	-	-	-	3.0	0.1	-	520	42	2	Good
Conventional sample	21	Cu-Cr	-	-	-	-	-	-	0.2	330	94	9	Good
	22	-	-	-	-	-	-	-	1.3	600	70	2	Good
	23	Kovar (Fe-29wt%Ni-17wt%Co)									20	78	Good

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	3	Cu-Sn	-	-	0.7	-	-	-	-	580	62	7	Good
	4	-	-	-	1.0	-	-	-	-	620	52	6	Good
	5	Cu-Sn	-	-	0.6	0.3	-	-	-	560	59	7	Good
	6	-Ag	-	-	1.0	0.3	-	-	-	640	50	6	Good
	7	Cu-Zn	0.1	-	-	-	2.1	0.1	-	440	68	13	Good
	8	-Fe-P	0.1	-	-	-	2.5	0.1	-	480	64	10	Good
	9	-	0.2	-	-	-	2.1	0.1	-	460	66	12	Good
	10	-	0.2	-	-	-	2.5	0.1	-	500	62	9	Good
	11	Cu-Cr	-	-	-	-	-	-	0.5	500	91	8	Good
	12	-	-	-	-	-	-	-	0.1	550	85	7	Good
Comparative Examples	13	Cu-Zn	0.02	0.04	-	-	-	-	-	370	88	9	Good
	14	-Mg	0.8	0.6	-	-	-	-	-	650	28	3	Good
	15	Cu-Sn	-	-	0.05	-	-	-	-	340	95	14	Good
	16	-	-	-	2.0	-	-	-	-	670	28	3	Good
	17	Cu-Sn	-	-	0.05	0.05	-	-	-	360	75	9	Good
	18	-Ag	-	-	2.0	1.0	-	-	-	680	30	3	Good
	19	Cu-Zn	0.03	-	-	-	1.8	0.1	-	360	70	13	Good
	20	-Fe-P	0.3	-	-	-	3.0	0.1	-	520	42	2	Good
	21	Cu-Cr	-	-	-	-	-	-	0.2	330	94	9	Good
	22	-	-	-	-	-	-	-	1.3	600	70	2	Good
Conventional Example	23	Kovar (Fe-29wt%Ni-17wt%Co)								580	20	78	Good

As is apparent from Table 1, No. 1 to No. 12 of Examples according to the present invention each had 50% IACS or more in conductivity and 400 MPa or more but 650 MPa or less in tensile stress. Further, the repeated bending property and the adhesion of Au plating were good. These indicated to have excellent characteristics as required for an IC lead pin for PGA provided on a plastic substrate.

On the other hand, in Comparative Examples, No. 13 had too small contents of Zn and Mg, No. 15 had a too small content of Sn, No. 17 had too small contents of Sn and Ag, No. 19 had too small contents of Fe and Zn, and No. 21 had a too small content of Cr, and thus, they each were quite low in tensile stress. Further, No. 14 had too large contents of Zn and Mg, No. 16 had a too large content of Sn, No. 18 had too large contents of Sn and Ag, No. 20 had too large contents of Fe and Zn, and No. 22 had a too large content of Cr, and thus, they each were poor in repeated bending property. In addition, the alloys in Nos. 14, 16, 18 and 20 were also poor in conductivity. These mean that all the alloys in the Comparative Examples were improper for an IC lead pin for PGAs.

The rod manufactured in Example 1 according to the present invention was subject to heading to form an IC lead pin for PGA, and a high-speed, high-density IC was

assembled using the resultant IC lead pin. The resultant
IC operated properly, and the IC lead pin for PGA was
neither bent nor broken when assembling. This is because
the IC lead pin for PGA had high conductivity and
5 excellent tensile stress and repeated bending property.

Having described our invention as related to the
present embodiments, it is our intention that the
invention not be limited by any of the details of the
10 description, unless otherwise specified, but rather be
construed broadly within its spirit and scope as set out
in the accompanying claims.